

# Single Line ESD Protection Diode Array UM5055 SOD523

#### **General Description**

The UM5055 ESD protection diode is designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and PDA's. It features large cross-sectional area junctions for conducting high transient currents, offers desirable electrical characteristics for board level protection, such as fast response time, lower operating voltage, lower clamping voltage and no device degradation when compared to MLVs.

The UM5055 ESD protection diode protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. The UM5055 is available in SOD523 package and with working voltages of 5 volt.

It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical. Additionally, it may be "sprinkled" around the board in applications where board space is at a premium. It may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 ( $\pm 15$ kV air,  $\pm 8$ kV contact discharge).

#### **Applications**

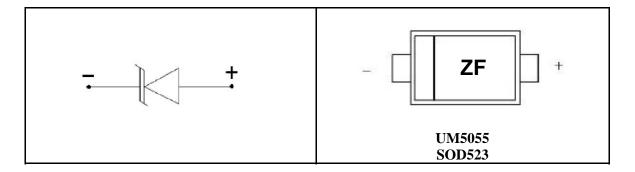
- Cell Phone Handsets and Accessories
- Microprocessor based equipment Personal Digital Assistants(PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Cordless Phones
- Digital Cameras
- Peripherals
- MP3 Players

#### **Features**

- Transient protection for data & power lines to IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- Small package for use in portable electronics
- Suitable replacement for MLV's in ESD protection applications
- Protect one I/O or power line
- Low clamping voltage
- Stand off voltage: 5V
- Low leakage current
- Solid-state silicon-avalanche technology

#### **Pin Configurations**

## **Top View**





### **Ordering Information**

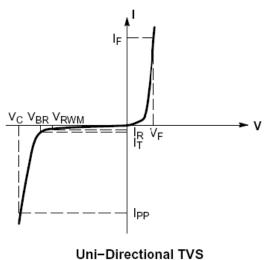
Part Number	Working Voltage	Packaging Type	Channel I		Shipping Qty
UM5055	5.0V	SOD523	1	ZF	3000pcs/7 Inch Tape & Reel

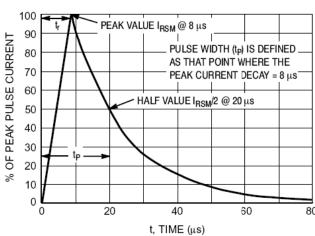
## **Absolute Maximum Ratings**

Rating	Symbol	Value	Units
Peak Pulse Power (tp = $8/20\mu$ s)	$P_{PK}$	140	Watts
Maximum Peak Pulse Current (t=8/20μs)	$I_{PP}$	11	Amps
Lead Soldering Temperature	$T_{ m L}$	260 (10 sec.)	°C
Operating Temperature	$T_{\mathrm{J}}$	-55 to +125	°C
Storage Temperature	$T_{STG}$	-55 to +150	°C

## **Symbol Definition**

Parameter	Symbol
Maximum Reverse Peak Pulse Current	$ m I_{PP}$
Clamping Voltage @ I <sub>pp</sub>	$V_{\rm C}$
Working Peak Reverse Voltage	$V_{ m RWM}$
Maximum Reverse Leakage Current @ V <sub>RWM</sub>	$I_R$
Breakdown Voltage @ I <sub>t</sub>	$ m V_{BR}$
Test Current	${ m I_t}$
Forward Current	$I_{\mathrm{F}}$
Forward Voltage @ I <sub>F</sub>	$V_{\mathrm{F}}$
Peak Power Dissipation	$P_{PK}$
Max. Capacitance @ $V_R = 0V$ , $f = 1MHz$	C







#### **Electrical Characteristics**

(T=25°C, Device for 5.0V Reverse Stand-off Voltage)

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse Stand-Off Voltage	$V_{RWM}$				5	V
Reverse Breakdown Voltage	$V_{BR}$	It = 1 mA	6	6.8	7.8	V
Reverse Leakage Current	$I_R$	$V_{RWM} = 5V$ , $T=25$ °C			0.1	μΑ
Clamping Voltage	$V_{\rm C}$	$I_{PP} = 5A, t_p = 8/20\mu S$ $I_{PP} = 11A, t_p = 8/20\mu S$			9.1	V
Forward Voltage	$V_{\mathrm{F}}$	$I_F = 10 \text{mA}$		0.8		V
Junction Capacitance	$C_{\mathrm{J}}$	$V_R = 0V$ , $f = 1MHz$		40	55	pF
Junction Capacitance	$C_{\mathrm{J}}$	$V_R = 2.5V, f = 1MHz$		30	40	pF

#### **Applications Information**

#### **Device Connection Options**

UM5055 ESD protection diode is designed to protect one data, I/O, or power supply line. The device is unidirectional and may be used on lines where the signal polarity is above ground. The cathode band should be placed towards the line that is to be protected.

#### Circuit Board Layout Recommendations for Suppression of ESD

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

- 1. Place the TVS near the input terminals or connectors to restrict transient coupling.
- 2. Minimize the path length between the TVS and the protected line.
- 3. Minimize all conductive loops including power and ground loops.
- 4. The ESD transient return path to ground should be kept as short as possible.
- 5. Never run critical signals near board edges.
- 6. Use ground planes whenever possible. For multilayer printed-circuit boards, use ground vias
- 7. Keep parallel signal paths to a minimum.
- 8. Avoid running protection conductors in parallel with unprotected conductor.
- 9. Minimize all printed-circuit board conductive loops including power and ground loops.
- 10. Avoid using shared transient return paths to a common ground point.

#### **Matte Tin Lead Finish**

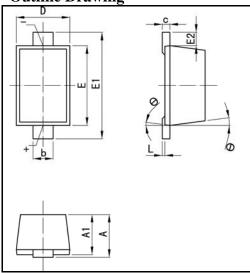
Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.



## **Package Information**

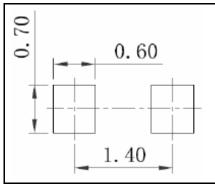
## **UM5055 SOD523**

**Outline Drawing** 



DIMENSIONS					
Symbol	MILLIMETERS		INCHES		
Syllibol	Min	Max	Min	Max	
A	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
c	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
Е	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200REF		0.008REF		
L	0.010	0.070	0.001	0.003	
θ	7°REF		7°REF		

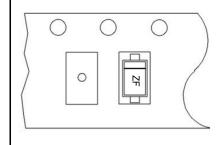
### **Land Pattern**



#### NOTES:

- 1. Compound dimension: 1.20×0.80;
- 2. Unit: mm;
- 3. General tolerance ±0.05mm unless otherwise specified;
  4. The layout is just for reference.

**Tape and Reel Orientation** 





#### **IMPORTANT NOTICE**

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